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Honjo et al.

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(54) **PATTERN FORMED ON THE GROUND LAYER OF A MULTILAYER PRINTED CIRCUIT BOARD**

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(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (8) Cl.** **13-03**
(52) **U.S. Cl.** **D13/182**
(58) **Field of Classification Search** D13/182; 174/254, 261; 428/209, 901; 439/55
See application file for complete search history.

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Primary Examiner—Selina Sikder
(74) *Attorney, Agent, or Firm*—Osha Liang LLP

(57) **CLAIM**

The ornamental design for a pattern formed on the ground layer of a multilayer printed circuit board, as shown and described.

DESCRIPTION

FIG. **1** shows a front view of the design according to a first embodiment of the present invention.

FIG. **2** shows a back view of the design according to a first embodiment of the present invention.

FIG. **3** shows a top plan view of the design according to a first embodiment of the present invention.

FIG. **4** shows a bottom plan view of the design according to a first embodiment of the present invention.

FIG. **5** shows a left side view of the design according to a first embodiment of the present invention.

FIG. **6** shows a right side view of the design according to a first embodiment of the present invention.

FIG. **7** shows a partial view of FIG. **1** corresponding to the area indicated by the dashed box in FIG. **1**.

FIG. **8** shows a detailed view of an enlarged portion of FIG. **7** indicated by the dashed box in FIG. **7**.

FIG. **9** shows a sectional view along the line **9**—**9** indicated in FIG. **7**.

FIG. **10** shows a front plan view of the design according to a second embodiment of the present invention. In this embodiment, the ground layer is transparent.

FIG. **11** shows a back view of the design according to a second embodiment of the present invention.

FIG. **12** shows a top plan view of the design according to a second embodiment of the present invention.

FIG. **13** shows a bottom plan view of the design according to a second embodiment of the present invention.

FIG. **14** shows a right side view of the design according to a second embodiment of the present invention.

FIG. **15** shows a left side view of the design according to a second embodiment of the present invention.

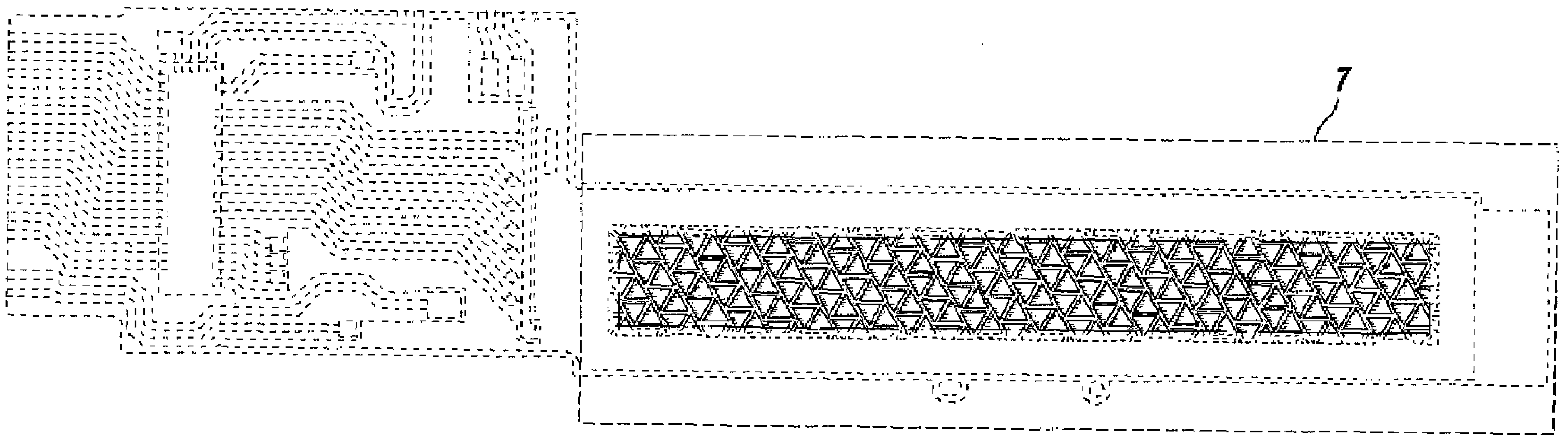
FIG. **16** shows a partial view of FIG. **11** corresponding to the area indicated by the dashed box in FIG. **11**.

FIG. **17** shows a detailed view of an enlarged portion of FIG. **17** indicated by the dashed box in FIG. **17**; and,

FIG. **18** shows a sectional view along the line **19**—**19** indicated in FIG. **17**.

The broken lines represent unclaimed subject matter.

1 Claim, 8 Drawing Sheets



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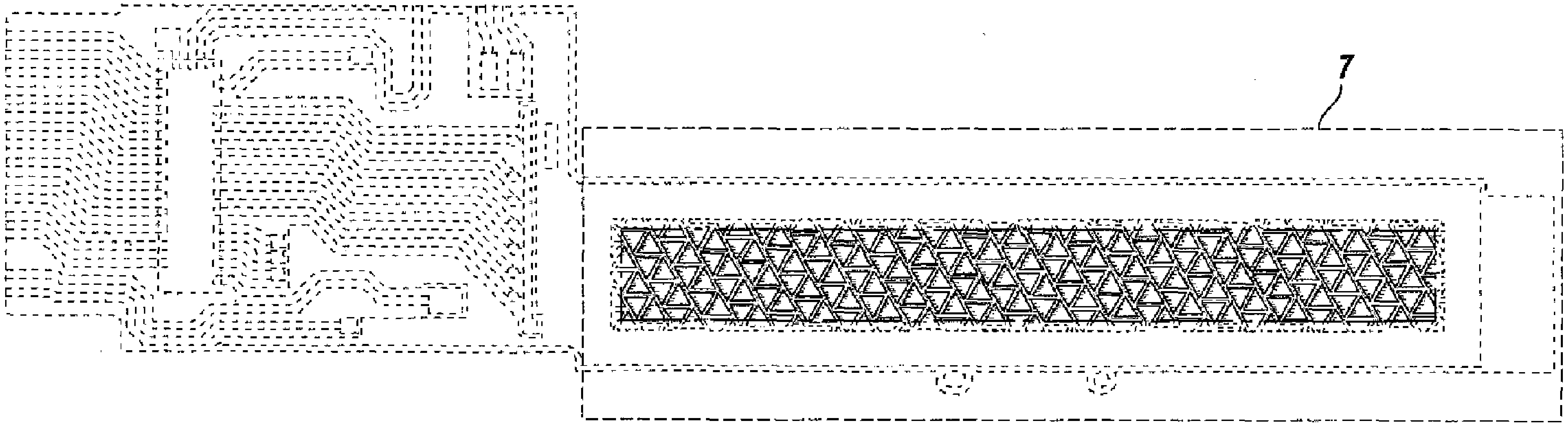

FIG. 1

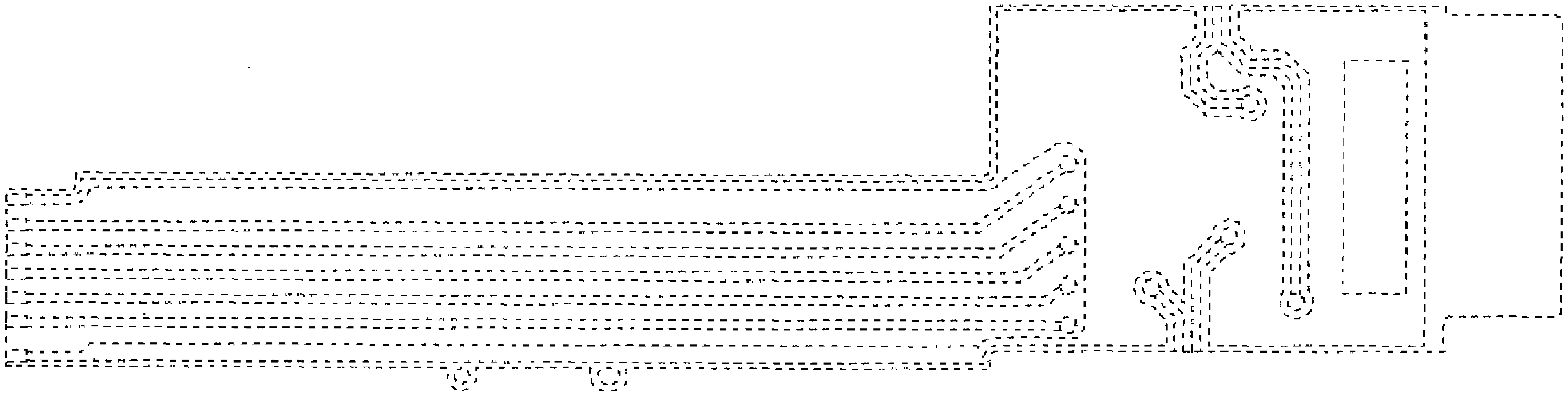

FIG. 2

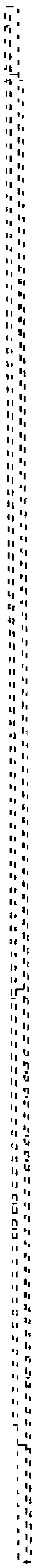

FIG. 3

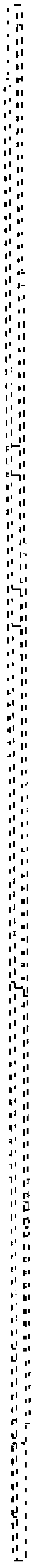

FIG. 4

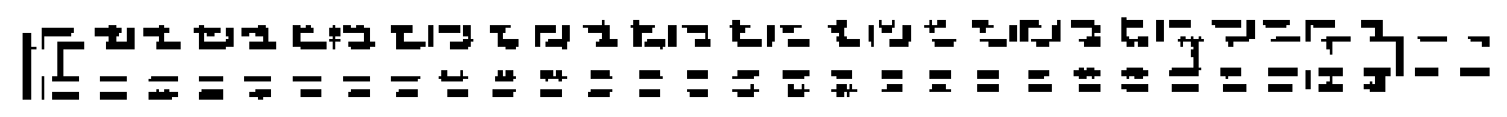

FIG. 5

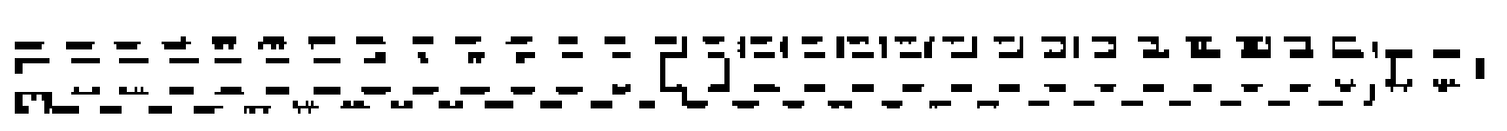

FIG. 6

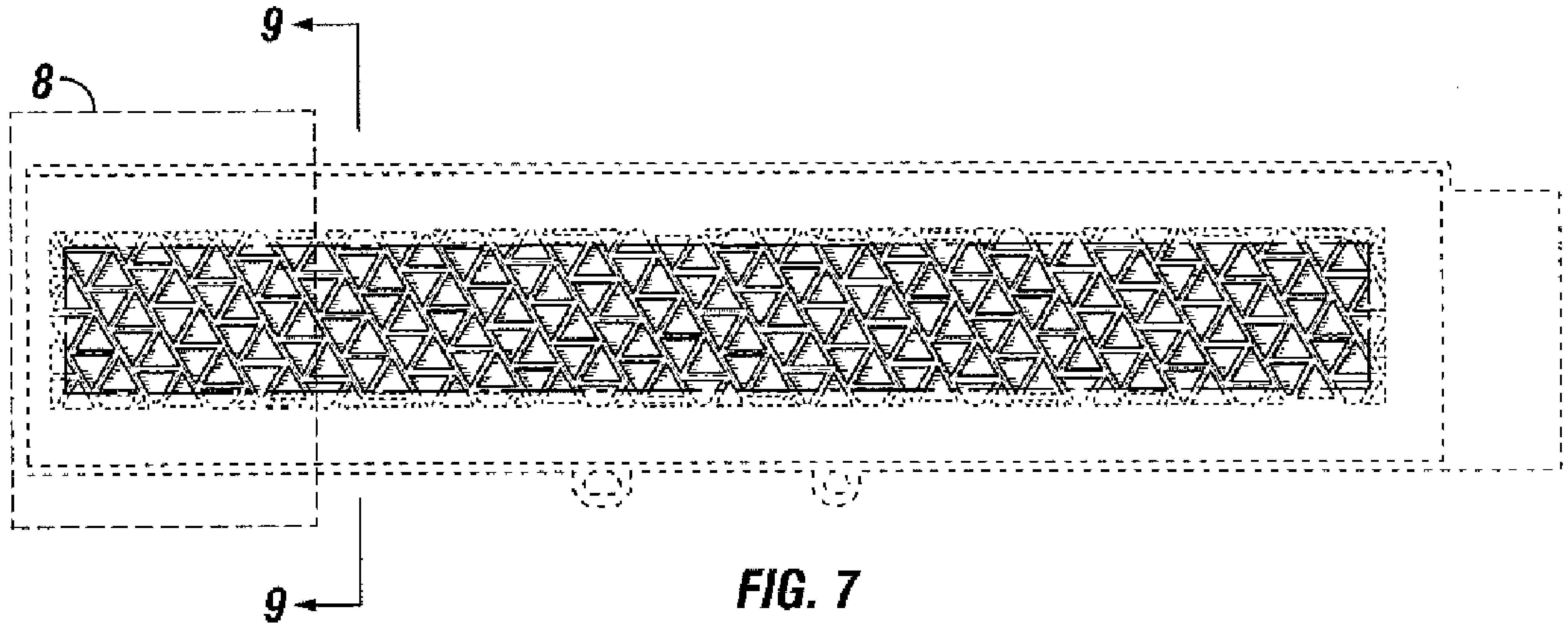

FIG. 7

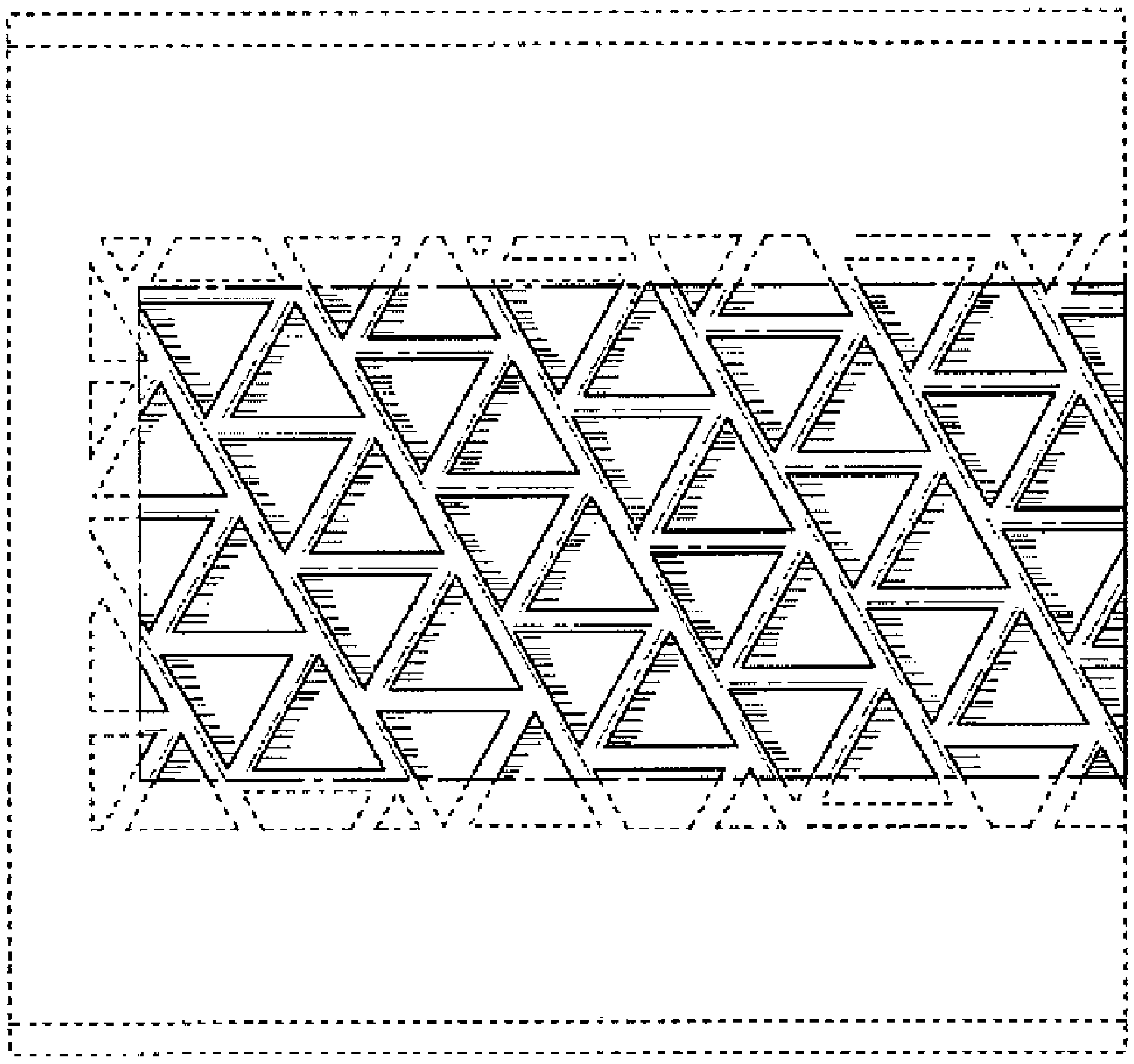

FIG. 8

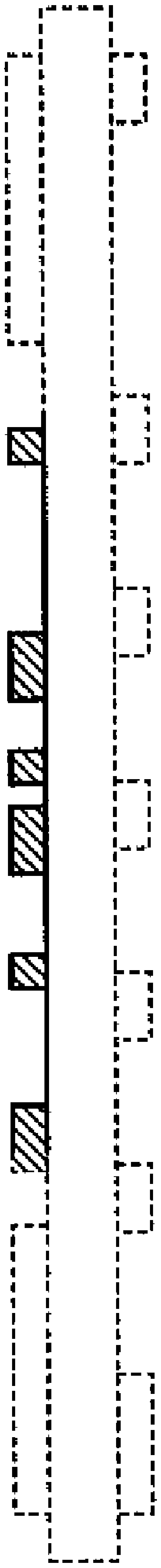

FIG. 9

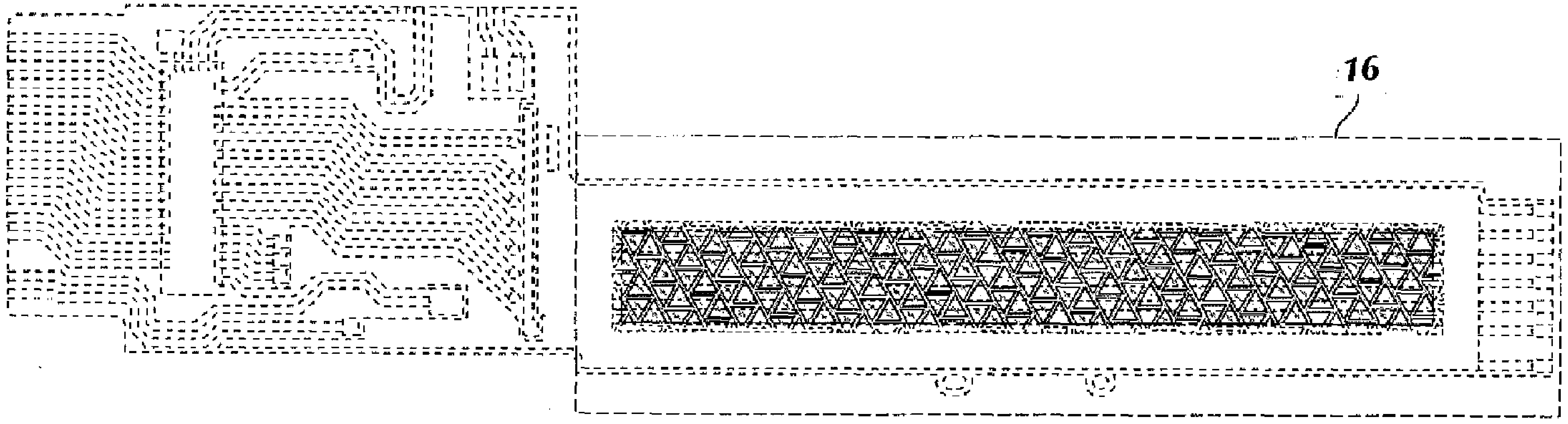

FIG. 10

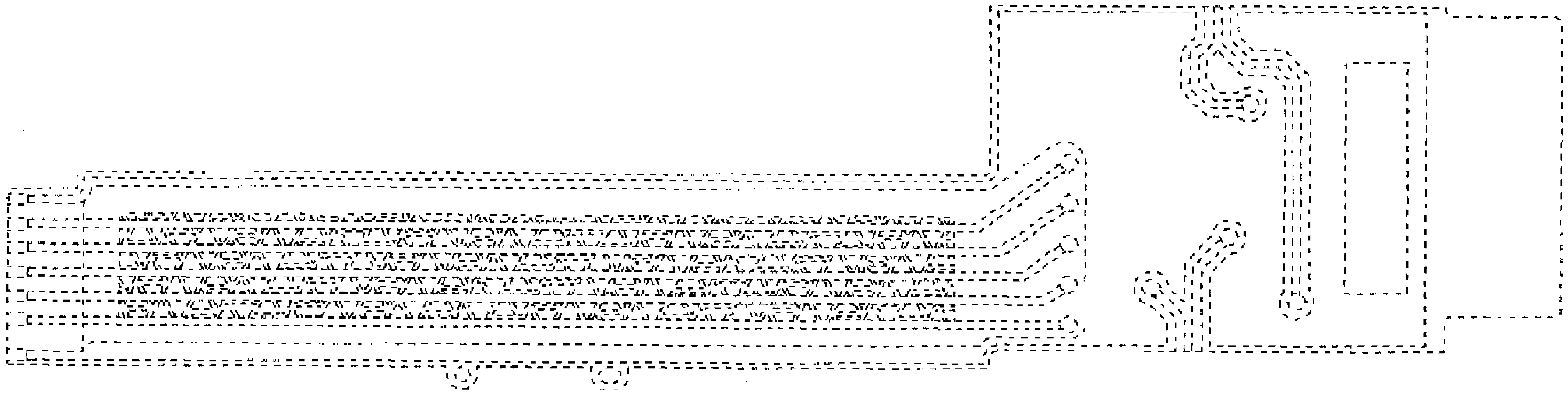

FIG. 11

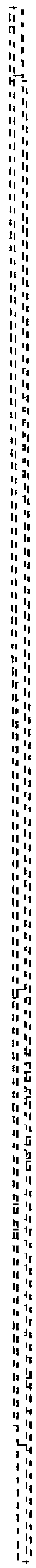

FIG. 12

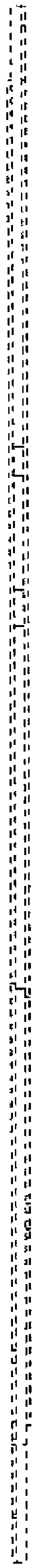

FIG. 13

FIG. 14

FIG. 15

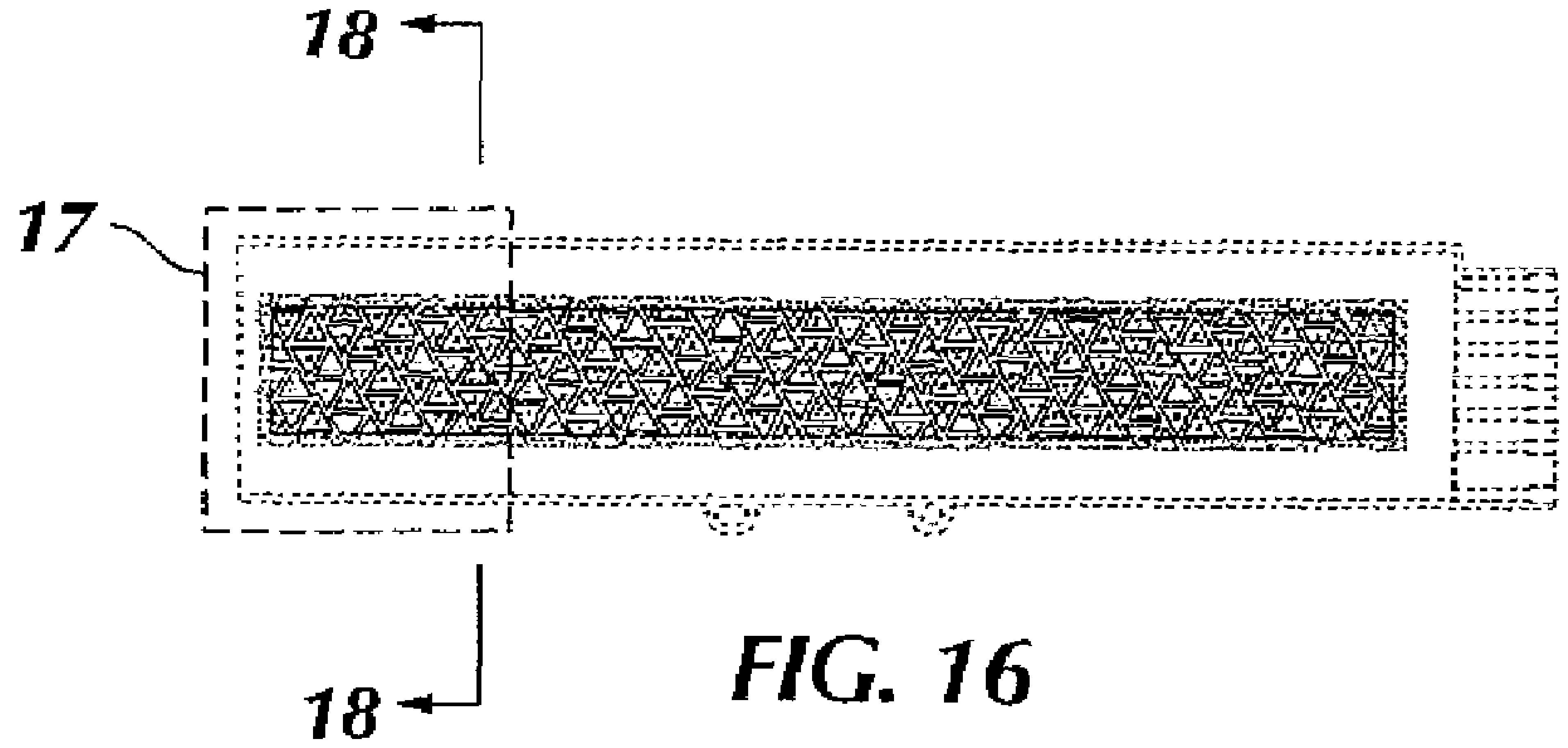

FIG. 16

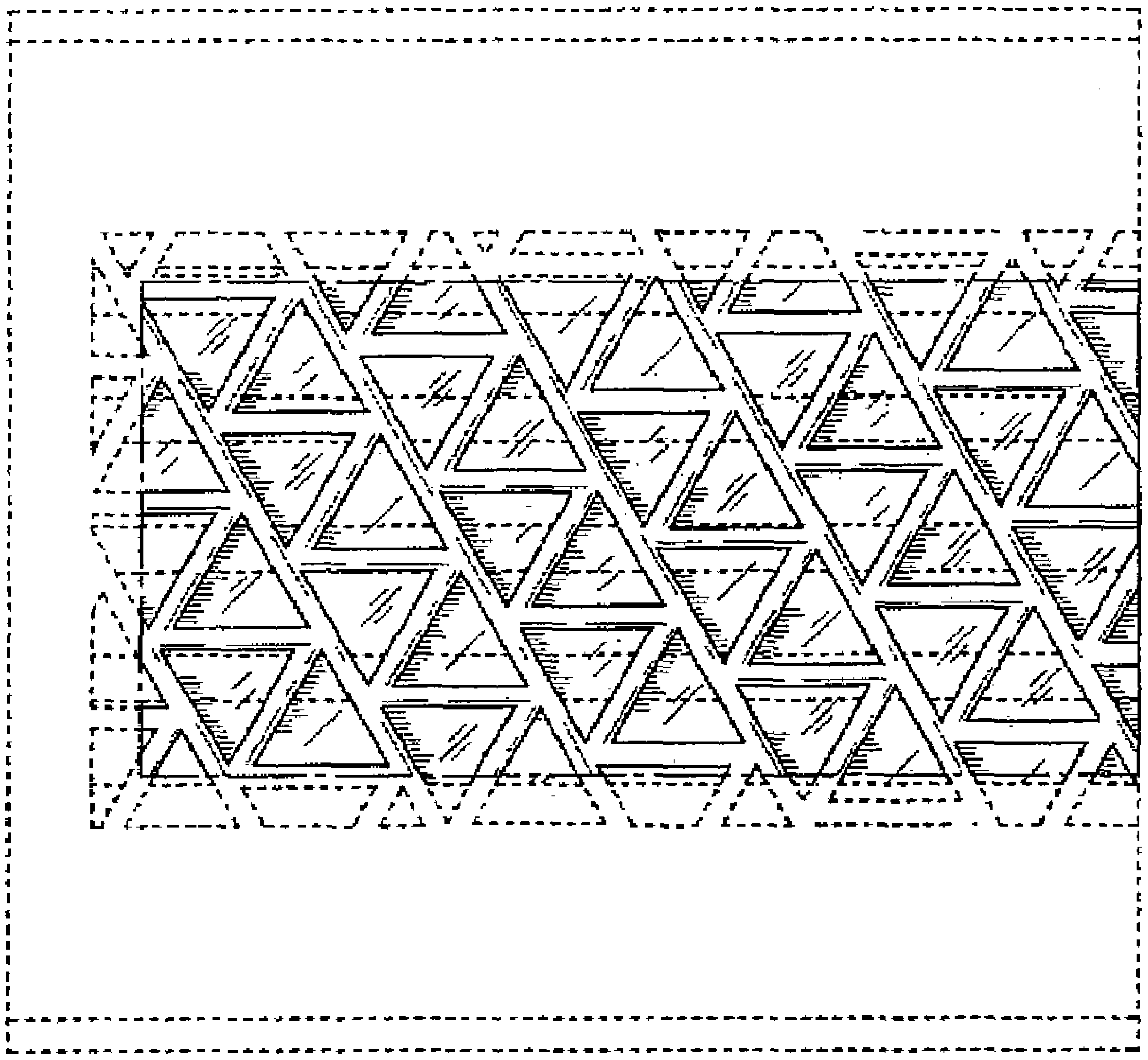

FIG. 17

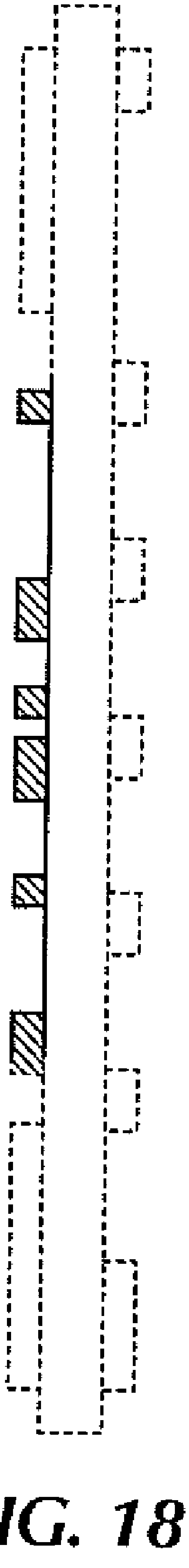

FIG. 18